

Standard Power MOSFETs

2N6898

Power MOS Field-Effect Transistors

**P-Channel Enhancement-Mode
 Power MOS Field-Effect Transistors**

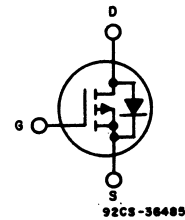
25 A, -100 V
 $r_{DS(on)}$: 0.20 Ω

- Features:**
- SOA is power-dissipation limited
 - Nanosecond switching speeds
 - Linear transfer characteristics
 - High input impedance
 - Majority carrier device

The 2N6898 is a P-channel enhancement-mode silicon-gate power MOS field-effect transistor designed for applications such as switching regulators, switching converters, motor drivers, relay drivers, and drivers for high-power bipolar switching transistors requiring high speed and low gate-drive power. This device can be operated directly from an integrated circuit.

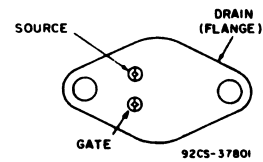
The 2N6898 is supplied in the JEDEC TO-204AE steel package.

TERMINAL DIAGRAM



P-CHANNEL ENHANCEMENT MODE

TERMINAL DESIGNATION

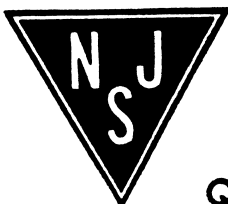


JEDEC TO-204AE

MAXIMUM RATINGS, Absolute-Maximum Values ($T_c = 25^\circ\text{C}$)

*DRAIN-SOURCE VOLTAGE, V_{DS}	-100 V
*DRAIN-GATE VOLTAGE ($R_{GS} = 1\text{ M}\Omega$), V_{DG}	-100 V
*GATE-SOURCE VOLTAGE, V_{GS}	± 20 V
*DRAIN CURRENT:	
RMS Continuous, I_D	25 A
Pulsed, I_{DM}	60 A
*POWER DISSIPATION, P_T :	
At $T_c = 25^\circ\text{C}$	150 W
Above $T_c = 25^\circ\text{C}$	Derate linearly 1.2 W/ $^\circ\text{C}$
*OPERATING AND STORAGE TEMPERATURE, T_j, T_{stg}	-55 to +150 $^\circ\text{C}$
*LEAD TEMPERATURE, T_L :	
At distances $\geq \frac{1}{8}$ in. (3.17 mm) from seating plane for 10 s max.	280 $^\circ\text{C}$

*In accordance with JEDEC registration data.



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ELECTRICAL CHARACTERISTICS at Case Temperature (T_c) = 25°C unless otherwise specified.

CHARACTERISTIC	TEST CONDITIONS	LIMITS		UNITS
		Min.	Max.	
Drain-Source Breakdown Voltage BV_{DSS}	$I_D = 1 \text{ mA}, V_{GS} = 0$	-100	—	V
Gate Threshold Voltage $V_{GS(th)}$	$V_{GS} = V_{DS}, I_D = 0.25 \text{ mA}$	-2	-4	V
Zero Gate Voltage Drain Current I_{DSS}	$V_{GS} = -80 \text{ V}$	—	1	μA
	$T_c = 125^\circ\text{C}, V_{DS} = -80 \text{ V}$	—	50	
Gate-Source Leakage Current I_{GSS}	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0$	—	100	nA
Drain-Source On Voltage $V_{DS(on)}^{\#}$	$I_D = 15.8 \text{ A}, V_{GS} = -10 \text{ V}$	—	3.16	V
	$I_D = 25 \text{ A}, V_{GS} = -10 \text{ V}$	—	-6	
Static Drain-Source On Resistance $r_{DS(on)}^{\#}$	$I_D = 15.8 \text{ A}, V_{GS} = -10 \text{ V}$	—	0.2	Ω
	$T_c = 125^\circ\text{C}, I_D = 15.8 \text{ A}, V_{GS} = 10 \text{ V}$	—	0.24	
Forward Transconductance $g_{fs}^{\#}$	$V_{DS} = -10 \text{ V}, I_D = 15.8 \text{ A}$	4	16	mho.
Input Capacitance C_{iss}	$V_{DS} = -25 \text{ V}$	—	3000	pF
Output Capacitance C_{oss}	$V_{GS} = 0 \text{ V}$	—	1500	
Reverse Transfer Capacitance C_{rss}	$f = 0.1 \text{ MHz}$	—	500	
Turn-On Delay Time $t_d(on)$	$V_{DS} = -50 \text{ V}$ $I_D = 12.5 \text{ A}$ $R_{\theta gn} = R_{\theta gs} = 50 \Omega$ $V_{GS} = -10 \text{ V}$	—	50	ns
Rise Time t_r		—	250	
Turn-Off Delay Time $t_d(off)$		—	400	
Fall Time t_f		—	250	
Thermal Resistance Junction-to-Case $R_{\theta jc}$		—	0.83	

SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS

CHARACTERISTIC	TEST CONDITIONS	LIMITS		UNITS
		Min.	Max.	
Diode Forward Voltage $V_{SD}^{\#}$	$I_{SD} = 25 \text{ A}$	0.8	1.6	V
Reverse Recovery Time t_{rr}	$I_F = 4 \text{ A}, dI_F/dt = 100 \text{ A}/\mu\text{s}$	—	750	ns

*In accordance with JEDEC registration data.

#Pulsed: Pulse duration = 300 μs max., duty cycle = 2%

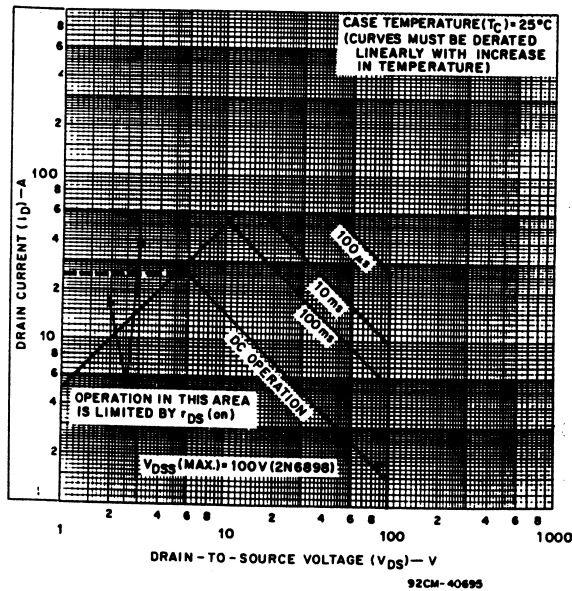


Fig. 1 - Maximum safe operating area.

